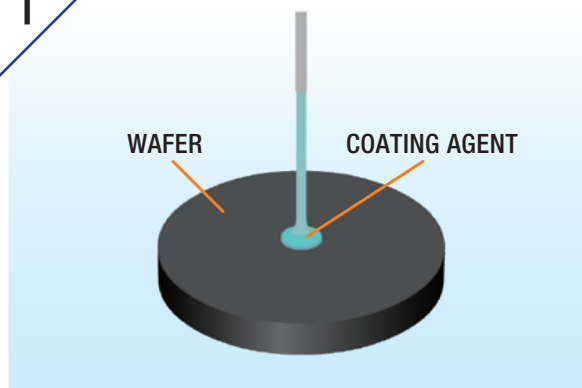
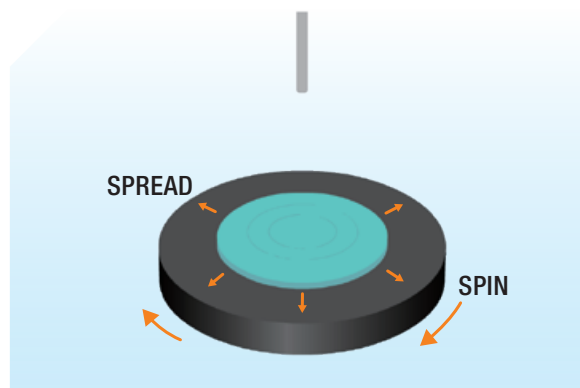


■ SURFACE PROTECTION OF PATTERNED SURFACE IN BACKSIDE CHEMICAL ETCHING PROCESS

1 旋涂



对安置于旋涂设备上的晶圆图形面涂布保护剂

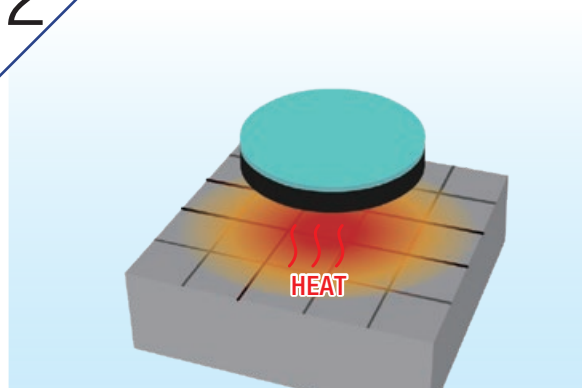


利用旋涂工艺将保护剂涂满晶圆



涂布的保护剂均匀成膜

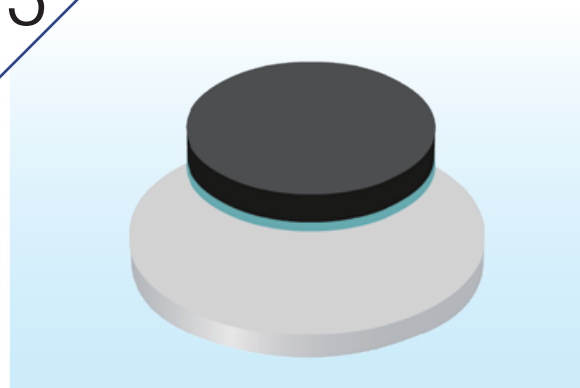
2 烘烤



用加热方式使保护剂中的溶媒挥发殆尽



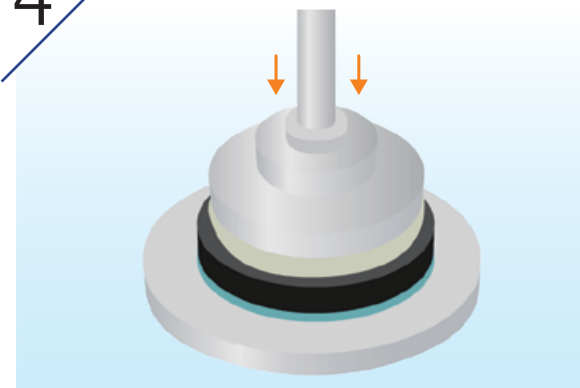
3 贴片



将加热的工件贴付至基板



4 加压



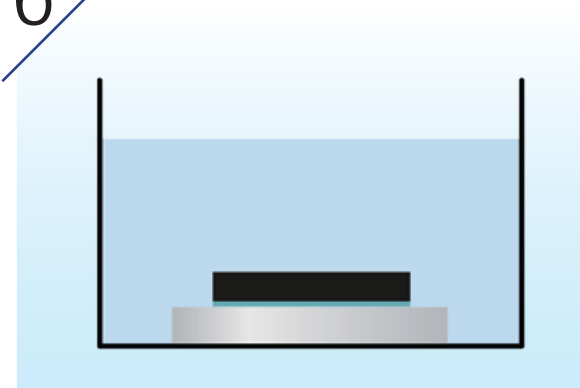
使晶圆平整地压在基板上完成贴付

5 冷却

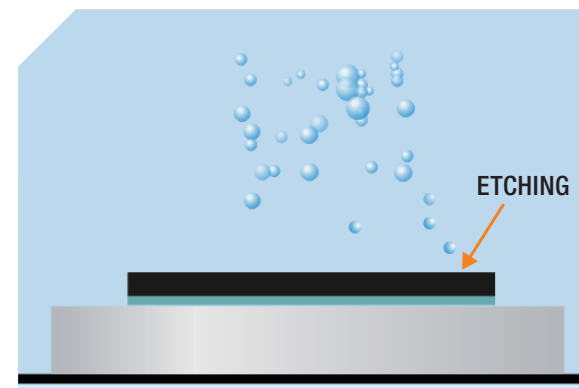


逐渐冷却工件与基板

6 蚀刻

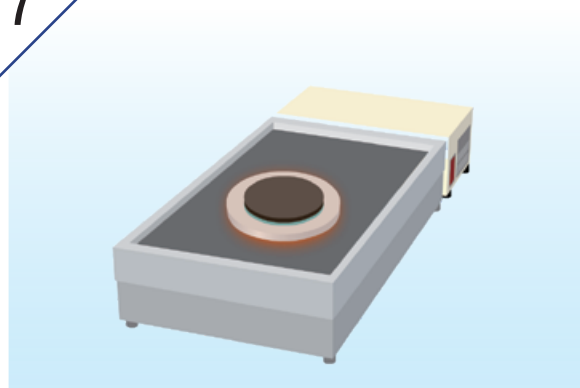


浸透至腐蚀液中

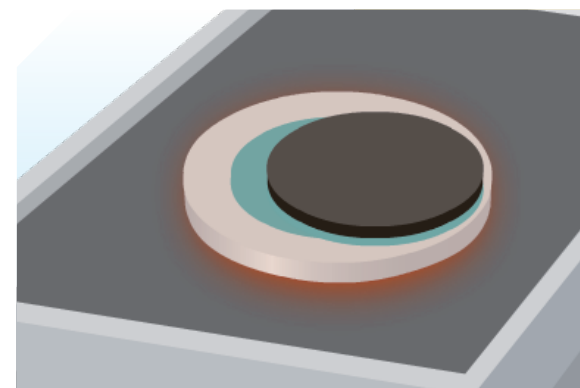


背面蚀刻/减薄加工

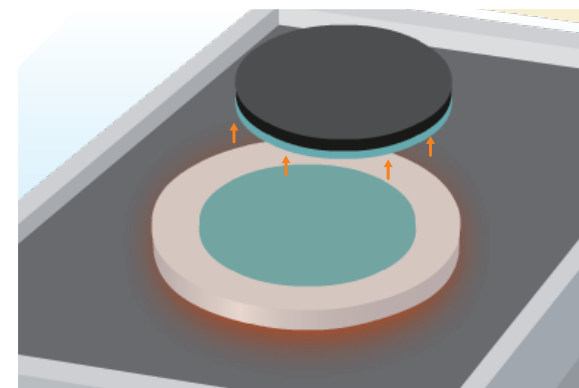
7 分离



用加热板进行加热

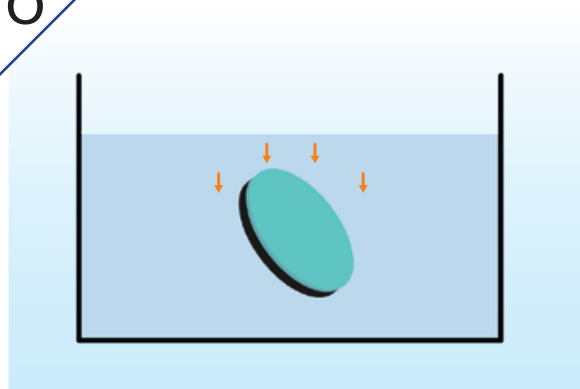


蜡层温度上升后变软,使工件变的可剥离

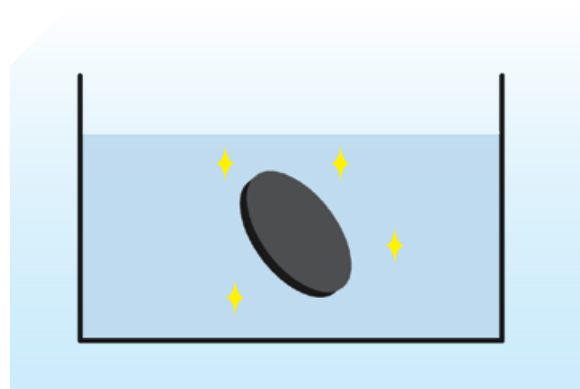


从基板剥离工件时请注意不要烫伤

8 清洗



将晶圆浸泡在清洗液中



蜡清洗完成



加工完成